

US 20190339249A1

(19) United States (12) **Patent Application Publication** (10) Pub. No.: US 2019/0339249 A1 DePalma et al. **(43) Pub. Date:** Nov. 7, 2019

(43) Pub. Date: Nov. 7, 2019

(54) CHARACTERIZATION AND CONTROL SYSTEM AND METHOD FOR A RESIN

- (71) Applicant: **General Electric Company**, Schenectady, NY (US)
- (72) Inventors: **Stephanie Lynn DePalma**,
Miamisburg, OH (US); **Michael Joseph**
O'Brien, Halfmoon, NY (US); **Brittany**
Nicole Potter, West Chester, OH (US)
- (21) Appl. No.: 16/512,787
- (22) Filed: **Jul. 16, 2019**

Related U.S. Application Data

 (63) Continuation of application No. 15/291,253, filed on Oct. 12, 2016, now Pat. No. 10,408,812.

Publication Classification

(52) U.S. Cl.
CPC **GOIN 33/442** (2013.01); **B29C 64/393** (2017.08); **GOIN 21/359** (2013.01); *GOIN* 2021/3595 (2013.01); **G01N 21/272** (2013.01); B33Y 50/02 (2014.12); B33Y 30/00 (2014.12)

(57) **ABSTRACT**
The present disclosure is directed to a method of altering chemical properties of an in-process resin used with a 3D
printing apparatus. The method includes monitoring the
in-process resin using an imaging spectrometer, comparing
the in-process resin and a model using one or more

150

FIC. 3

CHARACTERIZATION AND CONTROL SYSTEM AND METHOD FOR A RESIN

CROSS REFERENCE TO RELATED APPLICATIONS

[0001] This Application claims priority to, and is a continuation application of, U.S. patent application Ser. No. 15/291,253 filed Oct. 12, 2016 which is incorporated by reference in its entirety herein.

FIELD OF THE INVENTION

[0002] The present subject matter relates generally to control and alteration of chemical properties of a resin.

BACKGROUND OF THE INVENTION

[0003] Additive manufacturing or 3D printing is often used for creating models using a liquid photopolymer resin (resin). The models may further be used as casting molds, prototypes, patterns, or end products. 3D printing is able to create complex designs of a desired surface finish that may not otherwise be created through other machining or manu-
facturing methods. For example, stereolithography (SLA)
casting molds may be used to manufacture turbine airfoils.
[0004] When 3D printing is used to create casting quality of the model is at least in part dependent on the quality of the resin. While the quality, including chemical and physical characteristics, of the resin is generally known prior to production of models, as the resin ages, chemical and physical characteristics of the resin alter toward depletion, in which the resin loses its ability to produce models. Depletion of the resin results in an increased occurrence of model crashes, in which the resin of the model fails to properly cure or harden, resulting in a loss of geometry, tolerances, or desired surface finish, and ultimately discarding of the model and the resin. Depletion of the resin often occurs before the entire quantity of resin is consumed (i.e. the useful life of the resin is expiring before the physical quantity of resin is consumed), thereby resulting in wasted resin, scrapped models, and increased costs.

[0005] Therefore, a need exists for a system and method for controlling chemical properties of a resin as the resin ages.

BRIEF DESCRIPTION OF THE INVENTION

[0006] Aspects and advantages of the invention will be set forth in part in the following description, or may be obvious from the description, or may be learned through practice of the invention.

[0007] The present disclosure is directed to a method of altering chemical properties of an in-process resin used with a 3D printing apparatus. The method includes monitoring the in-process resin using an imaging spectrometer, comparing the in-process resin and a model using one or more spectrums from the imaging spectrometer, and diluting the in-process resin with a diluting resin.

[0008] A further aspect of the present disclosure is directed to a computer-implemented method of characterizing and altering chemical properties of an in-process resin used with a 3D printing apparatus. The computer-imple mented method includes receiving, by one or more computing devices, one or more first spectrums from an imaging spectrometer, in which the one or more first spectrums define at least one absorbance value versus a wavenumber for the in-process resin. The computer-implemented method further includes receiving, by one or more computing devices, one or more second spectrums from the imaging spectrometer, in which the one or more second spectrums define at least one absorbance value versus a wavenumber for a model. The computer-implemented method further includes identifying, by one or more computing devices, a standard peak based at least in part on comparing the one or more first spectrums and the one or more second spectrums; identifying, by one or more computing devices , at least one chemical constitu ent peak indicating depletion of a chemical constituent based and the one or more second spectrums; determining, by one or more computing devices , at least one peak ratio based at constituent peak; and generating, by one or more computing devices, a life cycle of the in-process resin based at least on an operating range of the at least one peak ratio.

[0009] A still further aspect of the present disclosure is directed to a system for characterizing and controlling chemical properties of an in-process resin. The system includes a 3D printing apparatus including the in-pr computing device configured to operate the 3D printing apparatus and the imaging spectrometer.

[0010] These and other features, aspects and advantages of the present invention will become better understood with reference to the following description and appended claims.
The accompanying drawings, which are incorporated in and constitute a part of this specification, illustrate embodiments of the invention and, together with the description, serve to explain the principles of the invention.

BRIEF DESCRIPTION OF THE DRAWINGS

[0011] A full and enabling disclosure of the present invention, including the best mode thereof, directed to one of ordinary skill in the art, is set forth in the specification, which makes reference to the appended figures, in which:

[0012] FIG. 1 is a diagram of an exemplary characterization and control system for a resin;

[0013] FIG. 2 is an exemplary spectrum from the exemplary system shown in FIG. 1;

[0014] FIG. 3 is an exemplary resin gradation generated from the exemplary system shown in FIG. 1;

[0015] FIG. 4 is an exemplary control chart generated from the exemplary system shown in FIG. 1;

[0016] FIG . 5 is a flowchart outlining steps performed by the disclosed method of characterization and control of chemical properties of a resin; and

[0017] FIG. 6 is another exemplary embodiment of a characterization and control system for a resin .

[0018] Repeat use of reference characters in the present specification and drawings is intended to represent the same or analogous features or elements of the present invention .

DETAILED DESCRIPTION OF THE **INVENTION**

[0019] Reference now will be made in detail to embodi-
ments of the invention, one or more examples of which are illustrated in the drawings. Each example is provided by way of explanation of the invention, not limitation of the invention. In fact, it will be apparent to those skilled in the art that various modifications and variations can be made in the present invention without departing from the scope or spirit of the invention. For instance, features illustrated or described as part of one embodiment can be used with another embodiment to yield a still further embodiment. Thus, it is intended that the present invention covers such modifications and variations as come within the scope of the mordifications and their equivalents.
 [0020] As used herein, the terms "first", "second", and

"third" may be used interchangeably to distinguish one component from another and are not intended to signify

location or importance of the individual components.
[0021] Characterization and control methods and systems
for chemical properties of a resin while in use with a 3D
printing apparatus is generally provided. The methods a systems of characterization improve upon resin characterization and control by determining a life cycle of the resin in use with a 3D printer and returning the resin to a known and repeatable chemical state. Restoration to known, repeatable, and quantifiable chemical properties mitigates model crashes and prevents resin waste due to depletion of the resin

prior to consumption of the resin.
[0022] Although the disclosure below references specific
chemical constituents and compositions of a photopolymer
resin, the present disclosure is applicable generally to resins
used for polymeric systems, including, but not limited to, stereo-
lithography (SLA), optical fabrication, photo-solidification, solid free-form fabrication, solid imaging, rapid prototyping, resin printing, fused deposition modeling (FDM), digital light processing (DLP), multi jet printing (MLP), and type printing.

[0023] Referring now to the drawings, FIG. 1 is an exemplary embodiment of characterization and control system for a resin 100 (herein referred to as "system 100 ") used with a 3D printing apparatus 110 (herein referred to as "3D printer 110"). The system includes the 3D printer 110, an imaging spectrometer 120, and a computing device 130. The 3D printer 110 produces one or more models 112. The 3D printer 110 may include a platform 113 immersed in a vat 114 filled with an in-process resin 116, as a liquid photopolymer resin, and a nozzle 118 . In one embodiment, the nozzle 118 exposes ultraviolet (UV) light to the in-process resin 116 in the vat 114 to produce the model 112 by curing the in-process resin 116. In various embodiments, the 3D printer 110 may further include an oven to bake the model 112 to further cure or harden the photopolymer resin within the model 112.

[0024] The system 100 further includes a computing device 130. The computing device 130 includes one or more processors 132 and one or more memory devices 134. The one or more memory devices 134 stores instructions 136 that, when executed by the one or more processors 132, cause the one or more processors to perform operations. The operations of the computing device 130 are further described herein.

[0025] In one embodiment of the system 100, the computing device 130 controls the 3D printer 110. In one example, a 3D model (e.g. CAD model) of a desired model 112 is uploaded to the computing device 130. The computing device 130 divides the 3D model into a multitude of thin layers. The computing device 130 controls, articulates, and operates the nozzle 118 to expose each thin layer of the in-process resin 116 to UV light, thereby curing the thin layer of the in-process resin $11\overline{6}$ into a portion of the model 112. The computing device 130 may further control, articulate, and operate the platform 113 within the vat 114. The platform 113 may rotate or translate to further expose each thin layer of the in-process resin 116 to UV light in conjunction with operation of the nozzle 118 .

[0026] In other embodiments of the 3D printer 110, the nozzle 118 deposits a quantity of the in-process resin 116 from the vat 114 onto the platform 113 . The computing device 130 controls the nozzle 118 to deposit a quantity of the in-process resin 116 over a multitude of thin layers. The nozzle 118 may further include a light emitting or heat

about 4000 cm^{-1} to about 400 cm^{-1} . In still another embodiemitting source to cure the in-process resin 116.
[0027] In another embodiment of the system 100, the
computing device 130 controls the imaging spectrometer
120. In various embodiments, the imaging spectrometer 120
is an i imaging spectrometer 120 is a Fourier transform infrared spectrometer employing a Fourier transform infrared spectroscopy technique. In one embodiment, the infrared spectrometer encompasses a near-infrared range of about 14000 cm⁻¹. In another embodiment, the infrared spectrometer encompasses a mid-infrared range of ment, the infrared spectrometer encompasses a far-infrared range of about 400 cm⁻¹ to about 10 cm⁻¹. In yet other embodiments, the infrared spectrometer may encompass a combination of overlapping ranges of the near-infrared, mid-infrared, or far-infrared ranges. In still yet other embodiments, the imaging spectrometer may define other ranges, conventions, or units to describe the portion of the electromagnetic spectrum in which the imaging spectrom-
eter operates.

[0028] The imaging spectrometer 120 outputs one or more first spectrums 121 defining at least one absorbance or emissions value versus a spectral range of wavenumbers for the in-process resin 116. The first spectrum 121 may define a percentage ranging from about 0 to about 100 , or its decimal equivalent, or any subset therebetween. The spectral range of wavenumbers may define a reciprocal centimeter. [0029] The imaging spectrometer 120 outputs one or more second spectrums 122 defining at least one absorbance or emissions value versus a spectral range of wavenumbers for the model 112. In one embodiment, the second spectrum 122 for the model 112 is produced from a model 112 from an unused or new in-process resin 116. For example, the second spectrum 122 is produced from the model 112 in which the in-process resin 116 is of known chemical or physical characteristics prior to use to produce a plurality of models 112 .

[0030] In various embodiment of the system 100 , the computing device 130 determines one or more chemical constituents of the in-process resin 116 and correlates the one or more chemical constituents of the in-process resin 116 to at least one chemical constituent peak of the first spectrum and/or second spectrum. In one embodiment, the computing device 130 determines the one or more chemical constituents of the in-process resin 116 using a table, graph, chart, or document. [0031] Referring now to FIG. 2, an exemplary embodi-

ment of a graph 200 of the first spectrum 121 and the second spectrum 122 is provided. In various embodiments, the first spectrum 121 and/or the second spectrum 122 may be provided in other formats, such as, but not limited to, comma separated value files, tables or tabulated data, spreadsheets, databases, or other graphical types, including at least an absorbance or emissions value corresponding to a wave

[0032] Referring to FIGS. 1 and 2, the computing device 130 of the system 100 identifies a standard peak based at least in part on comparing the one or more first spectrums and the one or more second spectrums. In one embodiment, the standard peak is identified by a plurality of chemical constituents contributing to the absorbance or emissions value of a peak of the first and/or second spectrum. In the exemplary embodiment shown in FIG. 2 , the computing device 130 outputs the graph 200 as an overlay of the first spectrum 121 and the second spectrum 122. The standard peak 212 may appear where at least a substantial portion of chemical constituents contribute to an absorbance or emis sions value 124 at a wavenumber value 125. In another embodiment in which the in-process resin 116 includes one or more chemical constituents defining an initiator chemical constituent and a reactive chemical constituent, the standard peak 212 may include a chemical bond that is common to the initiator chemical constituent and the reactive chemical constituent in the in-process resin 116. In yet another embodiment, the standard peak 212 may be defined as

having a substantially similar absorbance value 124 for the
first spectrum 121 compared to the second spectrum 122.
[0033] As a non-limiting example where the in-process
resin 116 and the model 112 include 4,4'-Isopropylid ethoxylated trimethylolpropane triacrylate esters; a mixed triarylsulfonium hexafluorophosphate salts in propylene car bonate; and a 1-hydroxycyclohexyl phenyl ketone, a carbonoxygen single bond stretch may appear in each chemical constituent and therefore contribute to the absorbance or emission value 124 of the standard peak 212 at a wavenumber 125 approximately similar between the first and second

[0034] Referring still to FIGS. 1 and 2, the computing device 130 of the system 100 identifies at least one chemical constituent peak 214 indicating depletion of a chemical constituent based at least in part on comparing the one or more first spectrums 121 and the one or more second spectrums 122. In various embodiments, the in-process resin 116 may include one or more of a solvent, an epoxy, and/or an oxetane.

[0035] In one embodiment, indications of depletion of a chemical constituent include indications of polymerization of the chemical constituents. In one embodiment including
the aforementioned chemical constituents, an ammonia
(CH) aromatic and a carbon-oxygen double bond in propylene carbonate may diminish from the first spectrum 121 to the second spectrum 122 at about the wavenumber for a chemical bond corresponding to a solvent in the initiator as
a result of the polymerization process from the in-process resin 116 to the model 112. In another embodiment, indications of depletion of a chemical constituent including the aforementioned chemical constituents may diminish a reactive in the second spectrum 122 versus the first spectrum 121. In still another embodiment, indications of depletion of a chemical constituent may include a change in wavenumber in the second spectrum 122 versus the first spectrum 121 for a reactive chemical constituent. For example, referring still to the aforementioned chemical constituents, the second spectrum 122 may include a diminished magnitude of absorbance of a reactive chemical constituent due to a depletion

of a carbon-oxygen single bond in an epoxy and/or oxetane.
[0036] Referring back to FIG. 1, the computing device 130 determines at least one peak ratio based at least in part on the standard peak and at least one chemical constituent peak . In one embodiment, the peak ratio is the absorbance of a chemical constituent peak divided by the absorbance at the standard peak. In another embodiment, the peak ratio is the absorbance of a reactive chemical constituent peak divided by the absorbance at the standard peak . In yet another embodiment, the peak ratio is the absorbance of an initiator chemical constituent peak divided by the absorbance at the

[0037] The system 100 generates a life cycle 140 of the in-process resin 116 based on at least an operating range of the at least one peak ratio. In various embodiments, the computing device 130 generates the life cycle 140 of the in-process resin 116 based on one or more control charts (such as a control chart 141 shown in FIG. 4). In one embodiment, the life cycle 140 includes at least one peak ratio from a reactive chemical constituent peak. In another embodiment, the life cycle 140 includes at least one peak ratio from an initiator chemical constituent peak. In various embodiments, the life cycle 140 may include an upper control limit, a lower control limit, and/or a moving range.
In other embodiments, the life cycle 140 may include an average moving range.

[0038] In various embodiments of the system 100, the computing device 130 generates the life cycle 140 of the in-process resin 120 including a resin gradation (such as a resin gradation 150 shown in FIG. 3) based at least on an operating range of the at least one peak ratio and one or more standard deviations of the at least one peak ratio. Referring now to FIGS. 1 and 3, in one embodiment, resin gradation 150 may be defined by ranges of peak ratios 152, 153 determined by the computing device 130. The resin gradation 150 may define a plurality of resin grades 151. In the embodiment shown in FIG. 3, the resin gradation 150 defines at (152) a Grade 1 resin by a first initiator peak ratio range less than I_1 ; a Grade 2 resin may be defined by a second initiator peak ratio range between I_1 and I_2 ; a Grade 3 resin may be defined by a third initiator peak ratio range between I_2 and I_3 ; and etc. until a Grade N resin may be defined by an Nth initiator peak ratio range between I_{N-1} and I_{N} . In another embodiment, the resin gradation 150 defines at (153) a Grade 1 resin may be defined by a first reactive peak ratio range less than $R₁$; a Grade 2 resin may be defined by a second reactive peak ratio range greater than R_1 ; a Grade 3 resin may be defined by a third reactive peak ratio range greater than R_2 ; and etc. until a Grade N resin may be

defined by reactive peak ratio range greater than R_{N-1} .
[0039] Referring now to FIGS. 1 and 4, the system 100 determines whether the in-process resin 116 is unexpired or expiring based at least on the life cycle 140 of the in-process resin 116. In one embodiment, the computing device 130 determines whether the in-process resin 116 is unexpired or expiring based at least on one or more control charts 141. The control chart 141 may include a time-dependent axis 142 and an axis of peak ratios 143. The control chart 141 may include one or more peak ratios 144. In various embodiments, the computing device 130 defines a peak ratio limit 145 at about or below which the in-process resin 116 is expiring. In one embodiment, the in-process resin 116 is expired when one or more peak ratios 144 is at about or below a peak ratio limit 145 defined by a lower control limit of the peak ratios. In another embodiment, the in-process resin 116 is expired when one or more peak ratios 144 is at about or below a peak ratio limit 145 defined by three standard deviations below a median. In still other embodi-
ments, the in-process resin 116 is expired when one or more peak ratios 144 corresponding to a reactive chemical constituent and/or an initiator chemical constituent is at about or below the peak ratio limit 145. In various embodiments, the peak ratios 144 are determined from a reactive chemical constituent or an initiator chemical constituent from the in-process resin 116.

[0040] Referring to FIGS. 3 and 4, in various embodi-
ments, the resin gradation 150 or the control chart 141 may further define resin grades 151 or ranges of peak ratios 152, 153 by a number of standard deviations from the median of a sample population of peak ratios of the first quantity of resin 120. As a non-limiting example, where the median peak ratio for the initiator chemical constituent is approximately 0.125 and approximately 99.7 percent (or three standard deviations) of a normal distribution of the sample population is desired to be captured of the peak ratios, a peak ratio at or below three standard deviations below the median may define a Grade 1 resin; a range from the median to three standard deviations below the median may define a Grade 2 resin; a range from the median to three standard deviations above the median may define a Grade β resin; a range of an additional three standard deviations above Grade 3 may define a Grade 4 resin; and a range of an additional three standard deviations above Grade 4 may define a Grade 5 resin. As another non-limiting example, a Grade 5 resin may
be defined by a range of peak ratios 152, 153 for a sample
population of the unused in-process resin 116 (i.e. not
previously used to create the model 112), or th resin 116 used approximately once (i.e. used once previously to create the model 112).

 $[0041]$ Referring to FIG. 1, the system 100 dilutes the in-process resin 116 with a diluting resin 117 based at least on whether the in-process resin 116 is unexpired or expiring. In various embodiments, diluting the in-process resin 116 with the diluting resin 117 includes employing a rule of mixtures. In one embodiment, the diluting resin 117 is an unused liquid photopolymer resin. In another embodiment, the diluting resin 117 is a previously used liquid photopolymer resin. In various embodiments, the diluting resin 117 includes similar chemical constituents as the in-process resin 116.

[0042] In various embodiments of the system 100, the computing device 130 receives one or more of a third spectrum 123 from the imaging spectrometer 120, in which the one or more third spectrum 123 defines at least one absorbance value versus a wavenumber for the diluting resin 117. The computing device 130 further determines at least one peak ratio for the diluting resin 117 based at least in part on the standard peak 212 and at least one chemical con

stituent peak identified with the in-process resin 116. The computing device 130 may further determine a range of peak ratios for the diluting resin 117 from which to dilute the in-process resin 116. $[0043]$ In one embodiment of the system 100, the com-

puting device 130 determines the range of peak ratios for the diluting resin 117 from which to dilute the in-process resin 116 using a rule of mixtures. In another embodiment, using a rule of mixtures may include using the at least one peak

ratio of the diluting resin 117 and using the at least one peak
ratio of the in-process resin 116.
[0044] As a non-limiting example, a rule of mixtures is
employed to calculate a quantity (e.g. weight, volume, etc.)
of the In one embodiment, a rule of mixtures is employed to determine a quantity of diluting resin 117 to achieve a desired peak ratio for the in-process resin 116. In another embodiment, a rule of mixtures is employed to determine a quantity of diluting resin 117 to achieve a desired resin grade 151 for the in-process resin 116 from the resin gradation 150.

[0045] Referring now to FIGS. 1-4, the diluting resin 117 and the one or more third spectrum 123 may be implemented, configured, or otherwise executed substantially similarly as described in referenced to the in-process resin 116 and/or the one or more first spectrum 121. Additionally, as shown in FIG. 4, the control chart 141 may further include post-dilution peak ratios 149 demonstrating the return of the chemical characterization of the in-process resin 116 to a known state following dilution with the diluting resin 117.

[0046] Referring now to FIG. 5, a flowchart outlining exemplary steps of a method to characterize and control chemical properties of an in-process resin 500 (herein referred to as "method 500") is provided. The flowchart of FIG. 5 may be implemented by one or more computing devices, such as the computing device 130 depicted and described relative to FIGS. 1 and 6. FIG. 5 depicts steps performed in a particular order for the purposes of illustration and discussion. Those of ordinary skill in the art, using the disclosures provided herein, will understand that various steps of any of the methods disclosed herein can be adapted, modified, rearranged, omitted, or expanded in various ways
without deviating from the scope of the present disclosure.
[0047] The method 500 can include monitoring an in-

process resin using an imaging spectrometer, comparing the in-process resin and a model using one or more spectrums from the imaging spectrometer, and diluting the in-process resin with a diluting resin. The method 500 can include at (502) receiving one or more first spectrums from an imaging spectrometer. The one or more first spectrums define at least one absorbance value versus a wavenumber for an in-
process resin. At (504), the method 500 can include receiving one or more second spectrums from the imaging spectrometer. The one or more second spectrums define at least one absorbance value versus a wavenumber for a model. For example, the one or more second spectrums 122 produced by the system 100 described in regard to FIGS. 1 and 2 may be produced from an imaging spectroscopy of the model 112 from the imaging spectrometer 120. The model 112 may from the imaging spectrometer 120. The model in the insertion of which may be desirably repeated with the in-process resin 116.

[0048] The method 500 can include at (506) identifying a standard peak based at least in part on comparing the one or more first spectrums and the one or more second spectrums. At (508), the method 500 can include identifying at least one chemical constituent peak indicating depletion of a chemical constituent based at least in part on comparing the one or In various embodiments, the method 500 may further include comparing the one or more first spectrums and the one or more second spectrums at corresponding wavenum bers. In one embodiment, comparing the one or more first spectrums and the one or more second spectrums may include comparing at ranges of wavenumbers to identify changes in magnitude of absorbance or emissions and/or identifying changes, or shifts, in wavenumbers relative to a magnitude of absorbance or emission.

[0049] The method 500 can include at (510) determining at least one peak ratio based at least in part on the standard peak and at least one chemical constituent peak. For instance, determining at least one peak ratio may include determining a peak ratio based on the standard peak and a reactive chemical constituent peak. In another instance, determining at least one peak ratio may include determining a peak ratio based on the standard peak and an initiator mining a peak ratio may include repeating one or more steps
of the method 500 over a period of time.
[0050] At (512) , the method 500 can include generating a

life cycle of the in-process resin based at least on an operating range of the at least one peak ratio. In one embodiment, generating the life cycle of the in-process resin includes generating a resin gradation based at least on an operating range of the at least one peak ratio and one or more

[0051] In various embodiments, the method 500 may further include at (514) determining whether the in-process resin is unexpired or expiring based at least on the life cycle of the in-process resin. For instance, determ the in-process resin is unexpired or expiring may include comparing a peak ratio to an operating range of the life cycle. In another instance, determining whether the ining a peak ratio to a resin gradation. In still another instance, determining whether the in-process resin is unexpired or expiring may include comparing a peak ratio to a lower limit.

[0052] In another embodiment, the method 500 may further include at (516) receiving one or more third spectrums from the imaging spectrometer. The one or more third spectrums define at least one absorbance value versus a wavenumber for a diluting resin. At (518) , the method 500 may include determining at least one peak ratio for the diluting resin based at least in part on the standard peak and
at least one chemical constituent peak identified with the in-process resin.
[0053] At (520), the method 500 may include determining

a range of peak ratios for the diluting resin from which to dilute the in-process resin. In one embodiment in which the vat 114 is limited by volume and/or weight, determining a range of peak ratios for the diluting resin from which to dilute the in-process resin includes determining a minimum peak ratio of the diluting resin sufficient to dilute the in-process resin to a desired peak ratio and within the constraints of the vat 114 or system 100. In another embodi ment, determining a range of peak ratios for the diluting
resin from which to dilute the in-process resin may include
determining a quantity of diluting resin of a known peak
ratio necessary to dilute the in-process resin

[0054] The method 500 may include at (521) determining a range of peak ratios to which to dilute the in-process resin. In one embodiment, a user may input to the computing device 130 a desired range of peak ratios to which to dilute the in-process resin 116. In another embodiment, the computing device 130 may determine a range of peak ratios to which to dilute the in-process resin 116 based at least on the life cycle 140. For instance, the range of peak ratios to which to dilute the in-process resin 116 may be a defined range from an operating range of the in-process resin 116. As another non-limiting example, the range of peak ratios 152, 153 may be determined or chosen from the life cycle 140,
such as, but not limited to, from the control chart or the resin
gradation.
[0055] The method 500 may include at (522) diluting the

in-process resin with a diluting resin based at least on whether the in-process resin is unexpired or expiring. For instance, the computing device 130 of the system 100 may transmit a signal to the 3D printer 110 to mix the diluting
resin 117 and the in-process resin 116 by determined quan-
tities and/or to determined ranges of peak ratios.
[0056] At (524), the method 500 may further inclu

process resin. At (526) , the method 500 may include correlating the one or more chemical constituents of the in process resin to at least one chemical constituent peak of the

[0057] In various embodiments, the method 500 or portions thereof may be performed iteratively. In one embodiment, the steps at (502), (504), (506), (508), (510), and (512) may be performed iteratively. In another embodiment, the aforementioned steps and (514) may be performed iteratively. In still another embodiment, the aforementioned steps may be performed and a portion of the steps, such as at (502) , (510) , (512) , and (514) may be performed iteratively thereafter.

[0058] Referring now to FIG. 6, another exemplary embodiment of a characterization and control system 100 for a photopolymer resin is provided. The system 100 may include a 3D printer 110, an imaging spectrometer 120, and a computing device 130. The system 100 may further include one or more networks 160 to communicate within the system 100 and/or externally of the system 100. The one
or more processors 132 can include any suitable processing device, such as a microprocessor, microcontroller, integrated
circuit, logic device, and/or other suitable processing device.
The one or more memory devices 134 can include one or more computer-readable media, including, but not limited to, non-transitory computer-readable media, RAM, ROM, hard drives, flash drives, non-volatile storage devices, and/or other memory devices.

[0059] The system 100 may communicate via one or more network (s) 160, which can include any suitable wired and/or wireless communication links for transmission of the com-
munications and/or data, as described herein. For instance, the network 160 may include a SATCOM network, ACARS network, ARINC network, SITA network, AVICOM network, a VHF network, a HF network, a Wi-Fi network, a WiMAX network, a gatelink network, etc.

[0060] The one or more memory devices 134 can store information accessible by the one or more processors 132, including computer-readable instructions 136 that can be executed by the one or more processors 132. The instruc tions 136 can be any set of instructions that when executed by the one or more processors 132, cause the one or more processors 132 to perform operations. In some embodiments, the instructions 136 can be executed by the one or more processors 132 to cause the one or more processors 132 to perform operations, such as any of the operations and functions for which the system 100 and/or the computing device 130 are configured, the operations for characterizing and controlling chemical properties of a photopolymer resin (e.g., method 400), as described herein, the system for generating the life cycle of a photopolymer resin and/or diluting a photopolymer resin (e.g., system 100), the characterization and control system for a photopolymer resin, and/or any other operations or functions of the one or more
computing device 130 . The instructions 136 can be software
written in any suitable programming language or can be
implemented in hardware. Additionally, and/ 138 that can be accessed by the processor(s) 132 . For example, the data 138 can include the first spectrum 121, the second spectrum 122, the third spectrum 123, the standard peak 212 , the chemical constituent peaks 214 , the absorbance or emissions values 124 , the wavenumber values 125 , the one or more ranges of peak ratios 152, 153, the life cycle 140, the control charts 141, the resin gradation 150, and/or any other data and/or information described herein.

[0061] The computing device 130 can also include a network interface 139 used to communicate, for example, with the other components of system 100 (e.g., via network 160). The network interface 139 can include any suitable components for interfacing with one or more networks, including for example, transmitters, receivers, ports, controllers, antennas, and/or other suitable components.

 $[0.062]$ The technology discussed herein makes reference to computer-based systems and actions taken by and information sent to and from computer-based systems. One of ordinary skill in the art will recognize that the inherent variety of possible configurations, combinations, and divisions of tasks and functionality between and among components. For instance, processes discussed herein can be implemented using a single computing device or multiple
computing devices working in combination. Databases,
memory, instructions, and applications can be implemented
on a single system or distributed across multiple syste Distributed components can operate sequentially or in parallel.

[0063] The systems 100 and methods 500 shown in regard
to FIGS. 1-6 and described herein may characterize and
control chemical properties of an in-process resin as the
chemical properties alter over time. The systems and m ods described herein may return the in-process resin to known and desirable chemical properties following altera tion to an unknown state. Additionally, the method of diluting the in-process resin with the diluting resin provides benefits over alternative methods. For example, since 3D printing, including vats, is generally limited by physical properties such as space, weight, or volume, the methods and systems disclosed may improve resin characteristics within a limited physical space. Additionally, the methods and systems disclosed may return the in-process resin to a known chemical state and known state of the in-process life cycle in contrast to other methods. Still further, the methods and systems disclosed may reduce waste, and thereby provide cost benefits, over other methods of dilution or characterization.

 $[0064]$ This written description uses examples to disclose the invention, including the best mode, and also to enable any person skilled in the art to practice the invention, including making and using any devices or systems and performing any incorporated methods. The patentable scope of the invention is defined by the claims, and may include other examples that occur to those skilled in the art. Such other examples are intended to be within the scope of the claims if they include structural elements that do not differ from the literal language of the claims, or if they include equivalent structural elements with insubstantial differences from the literal languages of the claims.
What is claimed is:

1. A method of altering chemical properties of an in process resin used with a 3D printing apparatus , the method comprising :

- monitoring the in-process resin using an imaging spectrometer;
- determining at least one peak ratio based at least in part on a standard peak and at least one chemical constituent peak ;
- generating a life cycle of the in-process resin based at least on an operating range of the at least one peak ratio:
- comparing the in-process resin and a model using one or more spectrums from the imaging spectrometer; and diluting the in-process resin with a diluting resin.
-
- 2. The method of claim 1, further comprising:
- identifying the standard peak based at least in part on comparing one or more first spectrums and one or more second spectrums from the imaging spectrometer.
-
- **3**. The method of claim **1**, further comprising: identifying the at least one chemical constituent peak indicating depletion of a chemical constituent based at least in part on comparing one or more first spectrums least in part on comparison on comparison spectrums from the imaging spectrometer.
 4. The method of claim 1, further comprising :

determining a range of peak ratios to which to dilute the
-
- in-process resin with the diluting resin.
5. The method of claim 1, further comprising:
-
- receiving one or more third spectrums from the imaging spectrometer, wherein the one or more third spectrums define at least one absorbance value versus a wavenumber for a diluting resin; and
determining the at least one peak ratio for the diluting
- resin based at least in part on the standard peak and the at least one chemical constituent peak identified with the in-process resin; and
- determining a range of peak ratios for the diluting resin
from which to dilute the in-process resin.

6. The method of claim 5, wherein determining the range of peak ratios for the diluting resin from which to dilute the in-process resin includes using a rule of mixtures.

determining a range of peak ratios to which to dilute the in-process resin with the diluting resin.

8. A computer-implemented method of characterizing and altering chemical properties of an in-process resin used with a 3D printing apparatus, the computer-implemented method comprising:

- receiving, by one or more computing devices, one or more first spectrums from an imaging spectrometer, wherein the one or more first spectrums define at least one absorbance value versus a wavenumber for the in
- process resin;
receiving, by one or more computing devices, one or more second spectrums from the imaging spectrometer, wherein the one or more second spectrums define at least one absorbance value versus a wavenumber for a model:
- identifying, by one or more computing devices, a standard peak based at least in part on comparing the one or more first spectrums and the one or more second spectrums:
- identifying, by one or more computing devices, at least one chemical constituent peak indicating depletion of a ing the one or more first spectrums and the one or more second spectrums;
- determining, by one or more computing devices, at least one peak ratio based at least in part on the standard peak and at least one chemical constituent peak; and
- generating, by one or more computing devices, a life cycle of the in-process resin based at least on an

operating range of the at least one peak ratio.
9. The computer-implemented method of claim 8, wherein generating the life cycle of the in-process resin includes generating a resin gradation based at least on an operating range of the at least one peak ratio and one or more

10. The computer-implemented method of claim 8, further comprising:
determining, by one or more computing devices, whether

the in-process resin is unexpired or expiring based at least on the life cycle of the in-process resin.

11. The computer-implemented method of claim $\mathbf{8}$, further comprising:

determining a range of peak ratios to which to dilute the

12. The computer-implemented method of claim 11, fur-
ther comprising:

- receiving, by one or more computing devices, one or more third spectrums from the imaging spectrometer, wherein the one or more third spectrums define at least one absorbance value versus a wavenumber for a
- determining, by one or more computing devices, at least one peak ratio for the diluting resin based at least in part on the standard peak and at least one chemical constituent peak identified with the in-process resin; and
- determining, by one or more computing devices, a range of peak ratios for the diluting resin from which to dilute the in-process resin.

13. The computer-implemented method of claim 12, wherein determining the range of peak ratios for the diluting resin from which to dilute the in-process resin includes using a rule of mixtures.
14. The computer-implemented method of claim 13,

wherein using a rule of mixtures includes using the at least one peak ratio of the diluting resin and using the at least one

15. The computer-implemented method of claim $\mathbf{8}$, fur-
ther comprising:

diluting, by one or more computing devices, the inprocess resin with the diluting resin based at least on the life cycle of the in-process resin.

16. The computer-implemented method of claim 8, further comprising:

determining, by one or more computing devices, one or more chemical constituents of the in-process resin; and

correlating, by one or more computing devices, the one or more chemical constituents of the in-process resin to at least one chemical constituent peak of the first spec

17. A system for characterizing and controlling chemical properties of an in-process resin, the system comprising:
a 3D printing apparatus including the in-process resin and

- configured to generate a model;
- an imaging spectrometer configured to output at least one spectrum defining at least one absorbance value versus a wavenumber for each of the in - process resin and the model; and
a computing device configured to operate the 3D printing
-

apparatus and the imaging spectrometer.
 18. The system of claim 17, wherein the 3D printing apparatus further includes a diluting resin, and wherein the computing device is configured to dilute the in-process resin with the diluting resin based at least on a life cycle of the in-process resin.

ste